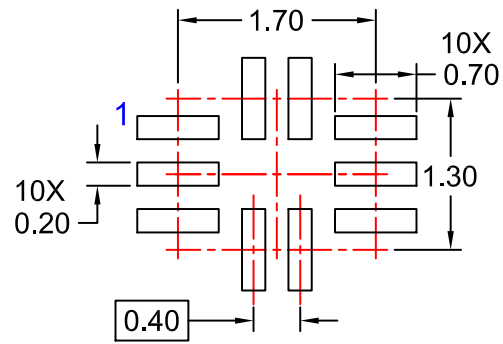
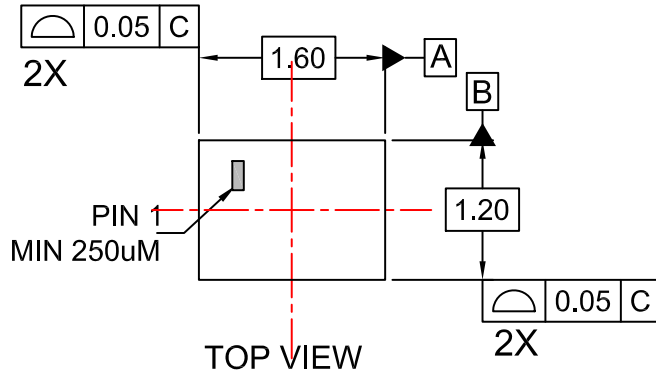


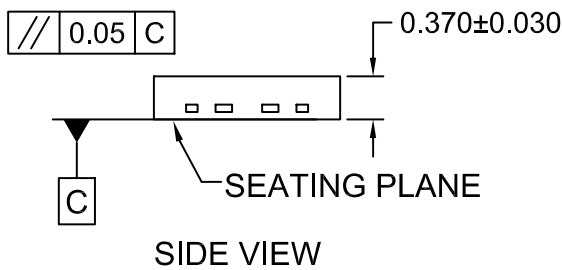


**X2QFN10 1.6x1.2, 0.4P**  
CASE 722AC  
ISSUE O

DATE 30 SEP 2016



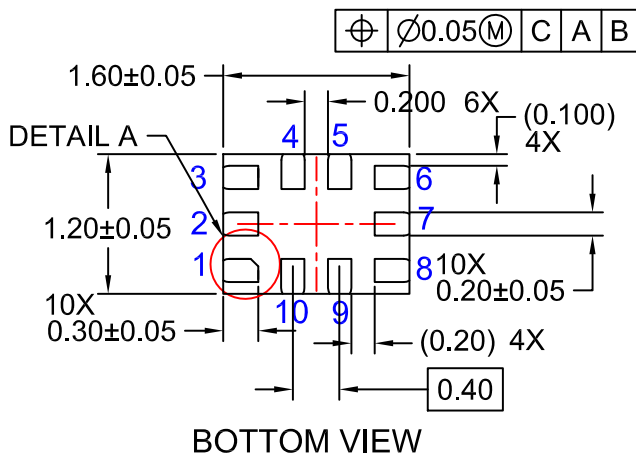
LAND PATTERN RECOMMENDATION



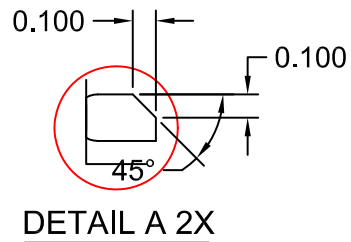
SIDE VIEW

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 2009.
- D. PACKAGE NOMINAL HEIGHT IS 370 MICRONS.



BOTTOM VIEW



DETAIL A 2X

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>X2QFN10 1.6x1.2, 0.4P</b>	<b>PAGE 1 OF 2</b>

